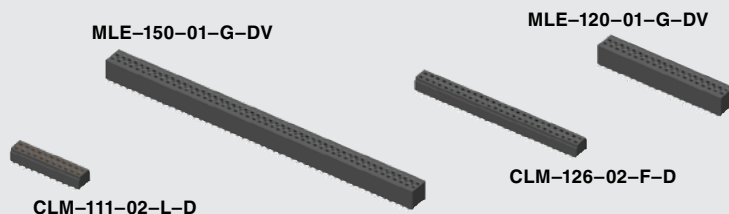




(1.00 mm) .0394"



CLM, MLE SERIES

RUGGED RELIABLE MICRO SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM or www.samtec.com?MLE

Insulator Material:

Black LCP

Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

Plating:

CLM: Au or Sn

over 50 μ" (1.27 μm) Ni

MLE: Au over 10 μ" (0.25 μm) Ni

Current Rating (CLM/FTM):

2.8 A per pin

(1 pin powered per row)

Current Rating (MLE/FTM):

2.9 A per pin

(1 pin powered per row)

Operating Temp Range:

-55 °C to +125 °C

Contact Resistance:

CLM: 15 mΩ

Max Cycles:

CLM: 100 with 10 μ" (0.25 μm) Au

Voltage Rating:

MLE: 310 VAC

Insertion Depth:

CLM: Top Entry = (1.40 mm)

.055" min., Bottom Entry =

(2.41 mm) .095" min.

(Add board thickness for correct post OAL)

MLE: (1.63 mm) .064" to

(3.18 mm) .125" with

(0.38 mm) .015" wiper,

pass-through, or

(2.44 mm) .096" minimum

for bottom entry

Normal Force:

CLM: 40 grams (0.39 N) average

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: Some lengths, styles and options are non-standard, non-returnable.

CLM

1 NO. PINS PER ROW

02

PLATING OPTION

D

OPTIONS

Mates with: FTM, FTMH, MW

02 thru 50

CLM

Insulator Material: Black LCP

Contact Material: CLM: Phosphor Bronze

MLE: BeCu

Plating: CLM: Au or Sn over 50 μ" (1.27 μm) Ni

MLE: Au over 10 μ" (0.25 μm) Ni

Current Rating (CLM/FTM): 2.8 A per pin (1 pin powered per row)

Current Rating (MLE/FTM): 2.9 A per pin (1 pin powered per row)

Operating Temp Range: -55 °C to +125 °C

Contact Resistance: CLM: 15 mΩ

Max Cycles: CLM: 100 with 10 μ" (0.25 μm) Au

Voltage Rating: MLE: 310 VAC

Insertion Depth: CLM: Top Entry = (1.40 mm) .055" min., Bottom Entry = (2.41 mm) .095" min. (Add board thickness for correct post OAL)

MLE: (1.63 mm) .064" to (3.18 mm) .125" with (0.38 mm) .015" wiper, pass-through, or (2.44 mm) .096" minimum for bottom entry

Normal Force: CLM: 40 grams (0.39 N) average

RoHS Compliant: Yes

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0.10 mm) .004" max (02-25) (0.15 mm) .006" max (26-50)

-F
= Gold flash on contact, Matte Tin on tail

-L
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-BE
= Bottom Entry (Required for bottom entry)

-K
= (3.50 mm) .138" DIA Polyimide film Pick & Place Pad (7 positions minimum)

-P
= Pick & Place Pad (7 positions minimum)

-PA
= Pick & Place Pad with integral Alignment Pin

-TR
= Tape & Reel Packaging

APPLICATION

Pass-Thru

PIN/ROW	A
04-15	(3.56) .140
16-50	(7.11) .280

MLE

1 NO. PINS PER ROW

01

PLATING OPTION

DV

OPTIONS

Mates with: FTM, FTMH, MW

02 thru 50

MLE

Insulator Material: Black LCP

Contact Material: MLE: BeCu

Plating: MLE: Au over 10 μ" (0.25 μm) Ni

Current Rating (MLE/FTM): 2.9 A per pin (1 pin powered per row)

Operating Temp Range: -55 °C to +125 °C

Contact Resistance: MLE: 15 mΩ

Max Cycles: MLE: 100 with 10 μ" (0.25 μm) Au

Voltage Rating: MLE: 310 VAC

Insertion Depth: MLE: Top Entry = (1.40 mm) .055" min., Bottom Entry = (2.41 mm) .095" min. (Add board thickness for correct post OAL)

MLE: (1.63 mm) .064" to (3.18 mm) .125" with (0.38 mm) .015" wiper, pass-through, or (2.44 mm) .096" minimum for bottom entry

Normal Force: MLE: 40 grams (0.39 N) average

RoHS Compliant: Yes

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0.10 mm) .004" max (02-25) (0.15 mm) .006" max (26-50)

-G
= 10 μ" (0.25 μm) Gold

-A
= Alignment Pin (3 positions minimum) Metal or plastic at Samtec discretion

-K
= (4.00 mm) .1575" DIA Polyimide film Pick & Place Pad (5 positions minimum)

-P
= Metal Pick & Place Pad (5 positions minimum)

-TR
= Tape & Reel Packaging

APPLICATION

Pass-Thru

PIN/ROW	A
04-15	(3.56) .140
16-50	(7.11) .280